

CLAIMS

What is claimed is:

1. A process comprising:
 - a) depositing a patterned film of polymer A on a substrate;
 - 5 b) depositing a thick film paste over the patterned film of polymer A;
 - c) drying of the thick film paste during which the patterned polymer A diffuses into the paste layer thus transferring the pattern to the paste layer; and
 - 10 d) removing the excess thick film paste from area absence of polymer A by exposing the paste layer to a paste developer solution which has poor solubility to polymer A.
2. A process comprising:
 - a) depositing a positive photo resist on a substrate
 - 15 b) masking a pattern on the resist
 - c) exposing the resist to light through the patterned mask
 - d) developing the resist
 - e) depositing thick film paste over the patterned photoresist
 - f) drying the thick film paste
 - 20 g) removing the excess thick film paste that has not mixed with the photo resist.
3. The process of Claim 1 or Claim 2 comprising the further step of firing the substrate patterned with the thick film paste.
4. The process of Claim 3 further comprising the step of activating
25 the thick film paste.
5. An electronic device fabricated by the process of Claim 1 or Claim 2.
6. The process of Claim 1 wherein polymer A is selected from the group consisting of phenolic resins, DNQ/Novalac resists, acrylic
30 polymers, polymers with pendent t-butyl groups, polystyrene, and ethyl cellulose.